

Amendments to the Specification

Please replace the paragraph beginning on page 8, line 15 with the following amended paragraph:

Referring to Figure 4, a solder joint having an intermetallic layer 27 formed between solder 25 and the pad 10 and an intermetallic boundary is shown. The pad 10 has the serpentine solder configuration depicted in Figure 3a. It will be observed that the respective micro-cracking 20 at each intermetallic boundary 15 is following a circuitous or meandering path. The lengthening of the crack pathway increases the useful life of the solder joint. Other pad configurations are shown in Figures 3b through 3d. As before, this results in micro-crack pathways that are interrupted, lengthened or constrained. In a similar manner, these configurations are expected to increase fatigue life of the solder joint, as is that of the solder design shown in Figure 3a.